

15A, 60V Schottky Barrier Surface Mount Rectifier

FEATURES

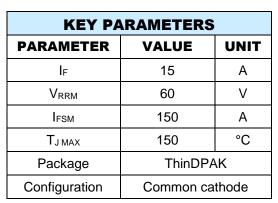
- AEC-Q101 qualified
- Low power loss, high efficiency
- Ideal for automated placement
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free

APPLICATIONS

- Low voltage, high frequency, inverter
- DC/DC converter
- Freewheeling diodes
- · Reverse battery protection
- Car lighting

MECHANICAL DATA

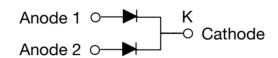
- Case: ThinDPAK
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- · Polarity: As marked
- Weight: 0.196g (approximately)







ThinDPAK



PARAMETER		SYMBOL	MBRAD1560DH	UNIT
Marking code on the device			1560D	
Repetitive peak reverse voltage		V _{RRM}	60	V
Reverse voltage, total rms value		V _{R(RMS)}	42	V
Forward current per device		l _F	15	А
Surge peak forward current single half sine wave superimposed on rated load per diode	t = 8.3ms	l _{FSM} -	150	Α
	t = 1.0ms		400	Α
Junction temperature		TJ	-55 to +150	°C
Storage temperature		T _{STG}	-55 to +150	°C

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THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-lead thermal resistance ⁽¹⁾	R _{OJL}	1.8	°C/W		
Junction-to-ambient thermal resistance ⁽²⁾	Reja	12.1	°C/W		
Junction-to-case thermal resistance ⁽²⁾	Reuc	2.5	°C/W		

Notes:

- 1. With ideal heat sink
- 2. Units mounted on 2" x 3" x 0.25" Al-plate

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage per diode ⁽¹⁾	I _F = 3.75A, T _J = 25°C		0.53	-	V
	I _F = 7.50A, T _J = 25°C	VF	0.66	0.75	V
	I _F = 3.75A, T _J = 125°C		0.48	-	V
	I _F = 7.50A, T _J = 125°C		0.57	0.64	V
Reverse current @ rated V _R per diode ⁽²⁾	T _J = 25°C	I_	-	100	μA
	T _J = 125°C	l _R	-	20	mA
Junction capacitance per diode	1MHz, V _R = 4.0V	Сл	253	-	pF

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE	PACKAGE	PACKING		
MBRAD1560DH	ThinDPAK	4,500 / Tape & Reel		



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.1 Forward Current Derating Curve

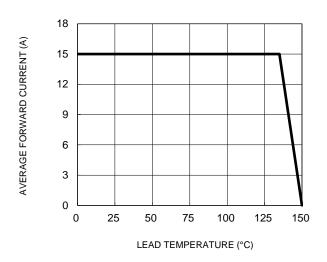


Fig.3 Typical Reverse Characteristics

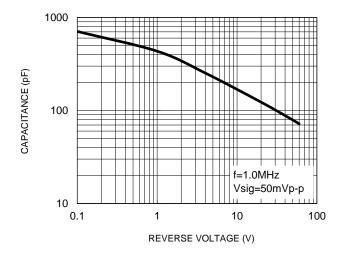
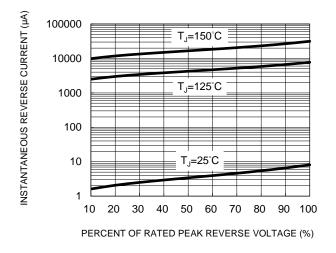


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



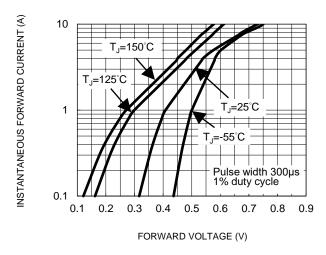
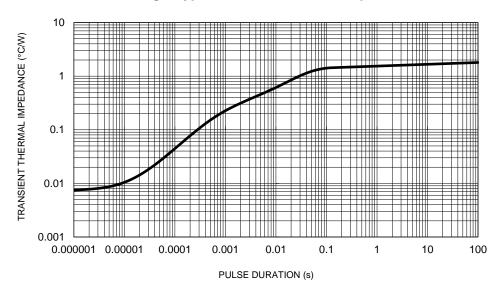


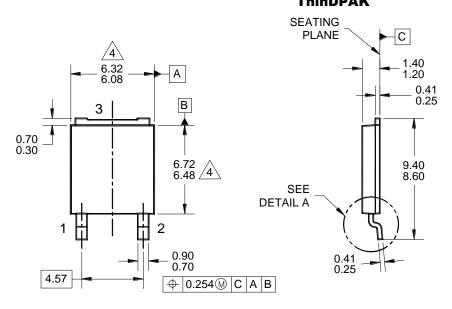
Fig.5 Typical Transient Thermal Impedance

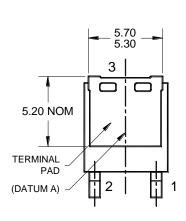


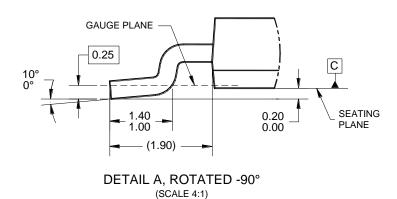


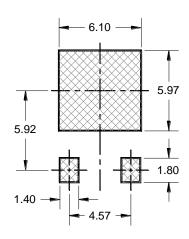
PACKAGE OUTLINE DIMENSIONS

ThinDPAK

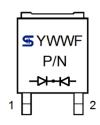








SUGGESTED PAD LAYOUT



MARKING DIAGRAM

YWW = DATE CODE F = FACTORY CODE P/N = MARKING CODE

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PACKAGE OUTLINE REFERENCE: JEDEC TO-252, VARIATION AE, ISSUE F.
- MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSION, OR GATE BURRS.
 - 5. DWG NO. REF: HQ2SD07-TDPAK-065 REV A.



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